



Product Change Notification

Change Notification #: 117686 - 00
Change Title: Intel® MAX® 10 Devices,
 PCN 117686-00, Documentation,
 Datasheet Update
Date of Publication: July 10, 2020

Key Characteristics of the Change:

Documentation

Forecasted Key Milestones:

Table 1

Availability of Intel MAX 10 device datasheet update	Now
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Description of Change to the Customer:

This is the same change described in ADV2026 issued on July 02, 2020.

Intel is notifying customers of an important documentation update for Intel MAX® 10 devices.

Below are the most recent changes listed in the document revision history of the Intel MAX 10 device datasheet.

Affected products	Change Description
10M02SCU324	<ul style="list-style-type: none"> - Table 52: Uncompressed Raw Binary File Size - Table 53: Internal Configuration Time for Intel MAX 10 Devices (Uncompressed. rbf) - Table 54: Internal Configuration Time for Intel MAX 10 Devices (Compressed. rbf)
10M02SCU324C8G, 10M04SCU324C8G, 10M08SCU324C8G, 10M16SCU324C8G, 10M16SCU169C8G, 10M16SAU169C8G, 10M16DCF484C8G, 10M16DAF484C8G, 10M25DCF484C8G, 10M25DAF484C8G, 10M40DCF484C8G, 10M40DAF484C8G, 10M50DCF484C8G, 10M50DAF484C8G	<p>Added the 1.0V LVCMOS I/O standard specification</p> <ul style="list-style-type: none"> - Table 6: Power Supplies Recommended Operating Conditions for Intel MAX10 Single Supply Devices - Table 7: Power Supplies Recommended Operating Conditions for Intel MAX10 Dual Supply Devices - Table 20: Single-Ended I/O Standards Specifications for Intel MAX 10 Devices

The Intel MAX 10 device datasheet can be found here:

https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/hb/max-10/m10_datasheet.pdf

Reason for Change:

Added the uncompressed Raw Binary File Size and Internal Configuration Time and the newly enabled 1.0V LVCMOS I/O standard feature. There is no change to the Intel MAX 10 device silicon and materials.

Customer Impact of Change and Recommended Action:

Customers are requested to take note of the changes and determine the impact on their designs.

For questions or support, please contact your local Field Applications Engineer (FAE), or submit a question or request at the My Intel support page, log-in via:

<https://www.intel.com/content/www/us/en/my-intel/fpga-sign-in.html>

Products Affected / Intel Ordering Codes:

The list of affected part numbers (OPNs) can be downloaded in Excel form:

<https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/adv2026-opn-list.xlsx>

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
July 10, 2020	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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